ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® International and Par	PC. Bannockl	burn, Illinois, A	Il rights reserved untions.	under both	This docume level parts, t	ent is a declaration entities the declaration entities and the declaration entities and the declaration entities and the declaration entities are an entities and the declaration entities are an entities and the declaration entities are an entite are an entities are an entities are an entite are	on of the su compasses	bstances v s all lower	vithin the manufactu level materials for v	urer listed which the	item. Note manufactur	: if the item is an as rer has engineering	sembly with low responsibility.	
			Form Type Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Inform					Afg Inform	ation				
upplier Information														
Company name* Company			y unique ID			Unique ID Authority				Respon	Response Date*			
onsemi										2025-0	2025-06-06			
ontact Name Title - Contact			ct		Phone - Contact*				Email - Contact*					
Product-Env-Stewards Product Envi			viro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Authorized Representative* Title - Repre			sentative			Phone - Representative*			Email	Email - Representative*				
Product-Env-Stewards Produc			oduct Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Requester Item Number	umber Mfr Item Number		er Mfr Item Name			Effective Date	Version	М	Manufacturing Site		Weight*	UOM	Unit Type	
	ES1JFL	ES1JFL SFR SOD123F PN		N 1A 600V		2025-06-06 TSCBE		SCBE	15.0		mg	Each		
Ianufacturing Proccess Informa	tion		·				·				•			
Terminal Plating / Grid Array M	aterial	al Terminal Base Alloy		J-STD-020 MSI	L Rating	Peak Proce	A Process Body Temperature Max Time at Peak		k Tempera	ature Nur	nber of Reflow Cyc	les		
Matte Tin (Sn) - annealed CU Alloy			1		260		С	30	seco	nds 3				
omments														
vel 1 - maximum time at peak temperatu	ure during so	dering is 10-3	0 seconds											
or more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declar	ation			Declaration Type *	Detailed
Directive 2015/863/EU amending Rol Directive 2011/65/EU	(Pb), Mercury (Hg), Hexav		ninated Biphenyls (PBB), Polybror	dmium and quantity limit of 0.1% by mass (100 ninated Diphenyl Ethers (PBDE), and Bis(2-eth	
cadmium, hexavalentchromium, polyb contains a RoHS restricted substance i encompass all such components.Suppl as of the date that Supplier completes Company acknowledges that Supplier independently verified information pro- certification in this paragraph.If the Co	rominated biphenyls and/or polybror nexcess of an applicable quantity lim ier certifies that it gathered the inforr this form.Supplier acknowledges that may have relied on informationprovi ovided by others, Supplier agrees that ompany and the Supplier enter into a clusivesource of the Supplier's liabili	ninated diphenyl ethers (each a "R it, please indicate below which, if nation it provides in this form usin Company will rely on this certifud ded by others in completing this f , at a minimum, itssuppliers have written agreement with respect to ty and the Company's remedies for	toHS restricted substance") in exce any, RoHS exemption you believe ag appropriate methods to ensure it cation in determining the complian orm, and that Supplier may not hav provided certifications regarding th the identified part,the terms and co or issues that arise regarding inform	ropean Union member states) of the part identifies so of the applicable quantity limit identified about may apply. If the part is an assembly with lows a accuracy and that such information is true and ce of its products with European Union member re independently verified such information. How heir contributions to the part, and those certifica motions of that agreement, including any warra nation the Supplier provides in this form. In the	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the inty rights and/or remedies provided as part of
<b>RoHS Declaration *</b> 4	- Item(s) does not contain RoHS restr	icted substances per the definition	above except for selected exempti	ons Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high meltin Exemption: 7c-I Electrical and elect	g temperature type solders (i.e. lead ronic components containing lead i	l based solder alloys containing n a glass or ceramic other than	85% by weight or more lead). dielectric ceramic in capacitors, o	e.g. piezoelectronic devices, or in a glass or ce	eramic matrix compound.
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the rec Requester) and click on Submit For			Supplier Acceptance drop-down	. This will display the signature area. Digital	ly sign the declaration (if required by the
Supplier Digital Signature	Rastislav Drska	Le			

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select	the Level (JIG A, JIG B	, Requester or Supplier) [B	] select the substa	ance category (JIG or Requester) or enter a	value (Supplier). [C] select	t the substance (JI	G) or enter the substa	nce and CAS (Other). [D]
select a RoHS exemption, if applied sigma range of distribution unless	cable [E] enter the weigh otherwise noted).	nt of the substance or the P	PM concentration	n [F] Optionally enter the positive (+) and n	egative (-) tolerance in per	cent (Note: percer	t tolerance values are	expected to cover a 3
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	1.52	mg	Supplier	Copper (Cu)	7440-50-8		1.52	mg
Die	0.997	mg	Supplier	Silicon (Si)	7440-21-3		0.8973	mg
			В	Nickel (Ni)	7440-02-0		0.0065	mg
			Supplier	Gold (Au)	7440-57-5		0.0015	mg
			Supplier	Lead Bisilicate	65997-18-4	7c	0.0917	mg
Die Attach Solder	0.408	mg	Supplier	Silver (Ag)	7440-22-4		0.0102	mg
			А	Lead (Pb)	7439-92-1	7a	0.3774	mg
			Supplier	Tin (Sn)	7440-31-5		0.0204	mg
Lead Frame	5.584	mg	Supplier	Iron (Fe)	7439-89-6		0.0056	mg
			Supplier	Copper (Cu)	7440-50-8		5.5767	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0017	mg
Mold Compound-Black	6.292	mg		Epoxy resin	proprietary data		0.3146	mg
			Supplier	Phenolic Resin	Proprietary Data		0.1258	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.1573	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0315	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		5.6628	mg
Plating	0.199	mg	Supplier	Tin (Sn)	7440-31-5		0.199	mg